MSEN 5353 - Integrated Circuit Packaging

MSEN 5353 Integrated Circuit Packaging (3 semester credit hours) Basic packaging concepts, materials, fabrication, testing, and reliability, as well as the basics of electrical, thermal, and mechanical considerations as required for the design and manufacturing of microelectronics packaging. Current requirements and future trends will be presented. General review of analytical techniques used in the evaluation and failure analysis of microelectronic packages. Prerequisite: MSEN 6324. (3-0) R